ASSOCIATION CONNECTING ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES® international and Pa	IPC. Bannockł	ourn. Illinois. A	ll rights reserved untions.	under both	This docume level parts, t	ent is a declaration en declaration	on of the su	bstances v all lower	vithin the manufactu level materials for v	urer listed which the	item. Note: manufacture	if the item is an as r has engineering	sembly with low responsibility.	
			Form Type Distribute	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Material				rials and N	ls and Mfg Information					
Supplier Information														
Company name* Company unit			ique ID t			Unique ID Authority				Respon	Response Date*			
onsemi										2024-0	2024-04-16			
ttact Name Title - Contact					Phone - Contact*				Email	Email - Contact*				
Product-Env-Stewards Product Enviro C			o Compliance		NA			Produ	Product-Env-Stewards@onsemi.com					
Authorized Representative* Title - Represen			entative		Phone - Representative*			Email	Email - Representative*					
Product-Env-Stewards Product En			Enviro Compliance			NA				Produ	Product-Env-Stewards@onsemi.com			
Requester Item Number	Requester Item Number Mfr Item N		Number Mfr Item Name			Effective Date	Date Version Manufacturing Site			Weight*	UOM	Unit Type		
	FDC653	DC653N 30V N-FET 35 MO		IO SSOT6		2024-04-16		РВВ			17.178	mg	Each	
Ianufacturing Proccess Informa	ntion		·									·		
Terminal Plating / Grid Array M	laterial 7	Terminal Base Alloy J-S		J-STD-020 MSI	Rating	Peak Process Body Tempera		emperature	ure Max Time at Peak Temp		ture Num	ber of Reflow Cyc	eles	
Matte Tin (Sn) - annealed CU Alloy			1		260		С	30	seco	nds 3				
omments														
vel 1 - maximum time at peak temperat	ure during so	ldering is 10-3	0 seconds											
or more information regarding material	l composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and co for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	on above	Supplier Acceptance	* Accepted							
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all						
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	stislav Drska	Le									

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3

sigma range of distribution unless	otherwise noted).					-		-
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.172	mg	Supplier	Silicon (Si)	7440-21-3		0.172	mg
Lead Frame	8.254	mg	Supplier	Silver (Ag)	7440-22-4		0.022	mg
			Supplier	Zinc (Zn)	7440-66-6		0.01	mg
			Supplier	Iron (Fe)	7439-89-6		0.198	mg
			Supplier	Copper (Cu)	7440-50-8		8.022	mg
			Supplier	Phosphorus (P)	7723-14-0		0.002	mg
Mold Compound-Black	7.596	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		2.2028	mg
			Supplier	Carbon Black (C)	1333-86-4		0.076	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		5.3172	mg
Plating	1.13	mg	Supplier	Tin (Sn)	7440-31-5		1.13	mg
Wire Bond - Au	0.026	mg	Supplier	Gold (Au)	7440-57-5		0.026	mg